Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!

Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832
Email & Skype: info@chipsmall.com Web: www.chipsmall.com
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

Littelfuse
Expertise Applied | Answers Delivered

Transient Voltage Suppression Diodes

Surface Mount – 600W > SMA6J series

SMA6J Series

Agency Approvals

AGENCY	AGENCY FILE NUMBER
UL	E230531

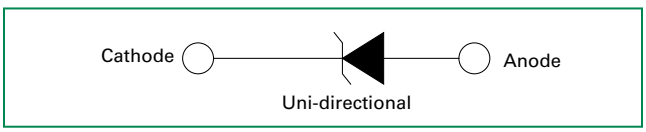
Maximum Ratings and Thermal Characteristics (T_A=25°C unless otherwise noted)

Parameter	Symbol	Value	Unit
Peak Pulse Power Dissipation at T_A=25°C by 10/1000µs Waveform (Fig.2)(Note 1), (Note 2)	P_{PPM}	600	W
Power Dissipation on Infinite Heat Sink at T_L=50°C	P_D	3.3	W
Peak Forward Surge Current, 8.3ms Single Half Sine Wave (Note 3)	I_{FSM}	60	A
Maximum Instantaneous Forward Voltage at 25A for Unidirectional Only	V_F	3.5	V
Operating Temperature Range	T_J	-65 to 150	°C
Storage Temperature Range	T_{STG}	-65 to 175	°C
Typical Thermal Resistance Junction to Lead	$R_{\theta JL}$	30	°C/W
Typical Thermal Resistance Junction to Ambient	$R_{\theta JA}$	120	°C/W

Notes:

1. Non-repetitive current pulse, per Fig.4 and derated above T_J (initial) =25°C per Fig. 3.
2. Mounted on 5.0x5.0mm copper pad to each terminal.
3. Measured on 8.3ms single half sine wave or equivalent square wave for unidirectional device only.

Functional Diagram



Description

The SMA6J series is designed specifically to protect sensitive electronic equipment from voltage transients induced by lightning and other transient voltage events.

Features

- 600W peak pulsepower capability at 10/1000µs waveform, repetition rate (duty cycle): 0.01%
- For surface mounted applications to optimize board space
- Low profile package
- Typical failure mode is short from over-specified voltage or current
- Whisker test is conducted based on JEDEC JESD201A per its table 4a and 4c
- IEC-61000-4-2 ESD 30kV(Air), 30kV (Contact)
- ESD protection of data lines in accordance with IEC 61000-4-2
- EFT protection of data lines in accordance with IEC 61000-4-4
- Built-in strain relief
- Glass passivated junction
- Low inductance
- Excellent clamping capability
- Fast response time: typically less than 1.0ps from 0 Volts to V_{BR} min
- Typical I_R less than 1µA when V_{BR} min>12V
- High temperature to reflow soldering guaranteed: 260°C/40sec
- V_{BR} @ T_J= V_{BR}@25°C x (1+αT x (T_J - 25)) (αT:Temperature Coefficient, typical value is 0.1%)
- Plastic package is flammability rated V-0 per Underwriters Laboratories
- Meet MSL level1, per J-STD-020, LF maximun peak of 260°C
- Matte tin lead–free plated
- Halogen free and RoHS compliant
- Pb-free E3 means 2nd level interconnect is Pb-free and the terminal finish material is tin(Sn) (IPC/JEDEC J-STD-609A.01)

Applications

TVS devices are ideal for the protection of I/O Interfaces, V_{CC} bus and other vulnerable circuits used in Telecom, Computer, Industrial and Consumer electronic applications.

Additional Infomarion

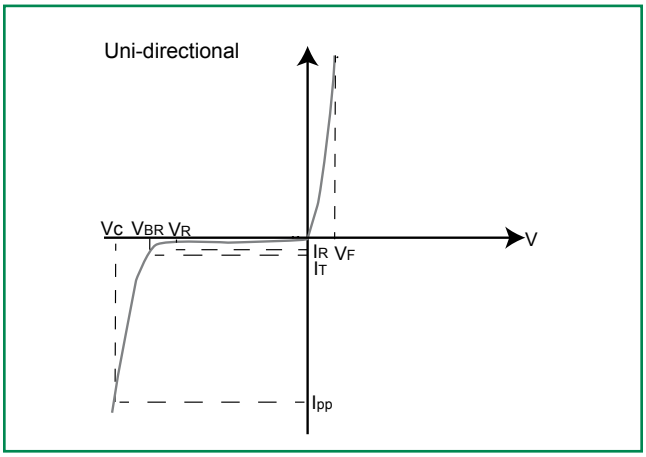
Datasheet | Resources | Samples

Revised: 11/20/15

Electrical Characteristics (T_A=25°C unless otherwise noted)

Part Number (Uni)	Marking	Reverse Stand off Voltage V_R (Volts)	Breakdown Voltage V_{BR} (Volts) @ I_T		Test Current I_T (mA)	Maximum Clamping Voltage V_C @ I_{pp} (V)	Maximum Peak Pulse Current I_{pp} (A)	Maximum Reverse Leakage I_R @ V_R (µA)	Agency Approval
	UNI		MIN	MAX					
SMA6J5.0A	6BA	5.0	6.40	7.00	10	9.2	65.3	800	X
SMA6J12A	6BE	12.0	13.30	14.70	1	19.9	30.2	1.0	X

I-V Curve Characteristics



P_{PPM} Peak Pulse Power Dissipation – Max power dissipation
V_R Stand-off Voltage – Maximum voltage that can be applied to the TVS without operation
V_{BR} Breakdown Voltage – Maximum voltage that flows though the TVS at a specified test current (I_T)
V_C Clamping Voltage – Peak voltage measured across the TVS at a specified Ippm (peak impulse current)
I_R Reverse Leakage Current – Current measured at V_R
V_F Forward Voltage Drop for Uni-directional

Ratings and Characteristic Curves (T_A=25°C unless otherwise noted)

Figure 1 - TVS Transients Clamping Waveform

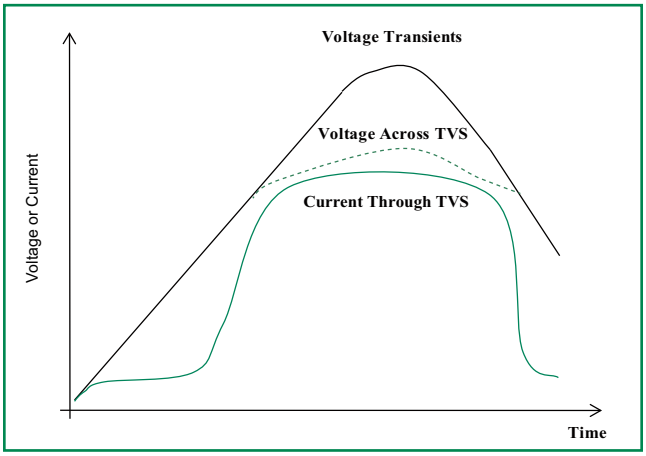
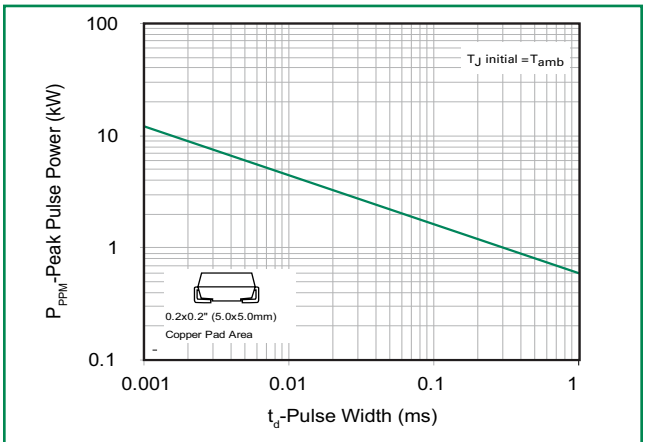


Figure 2 - Peak Pulse Power Rating Curve



continues on next page.

Revised: 11/20/15

Ratings and Characteristic Curves (T_A=25°C unless otherwise noted) (Continued)

Figure 3 - Peak Pulse Power Derating Curve

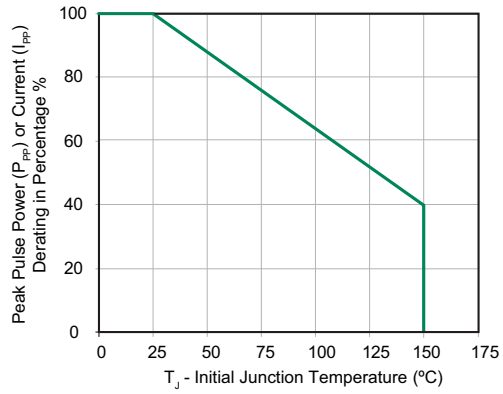


Figure 4 - Pulse Waveform

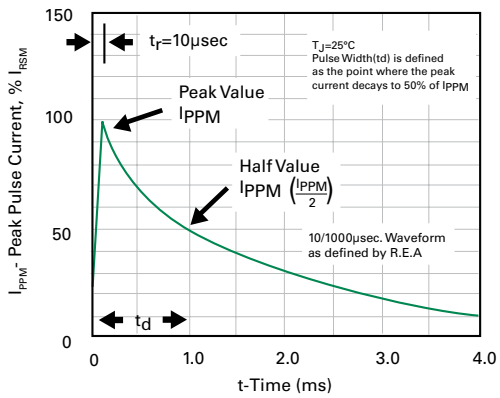


Figure 5 - Typical Junction Capacitance

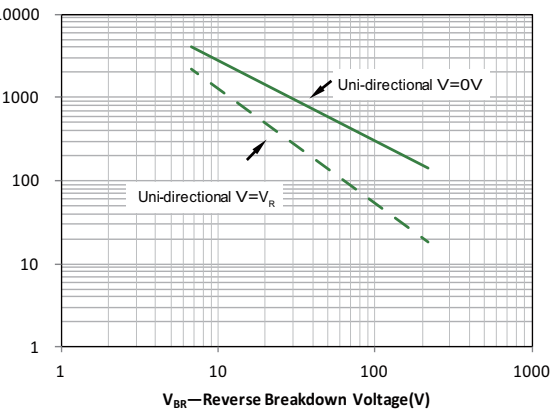


Figure 6 - Typical Transient Thermal Impedance

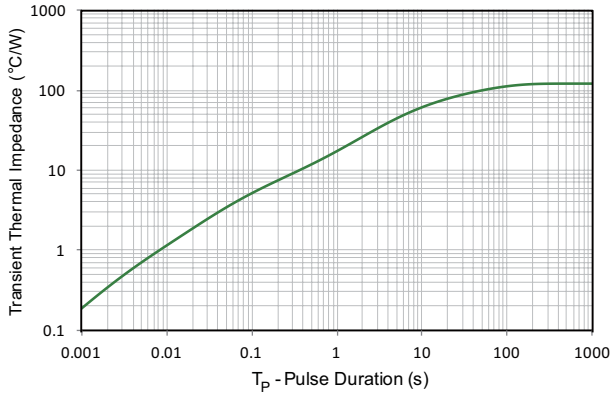


Figure 7 - Maximum Non-Repetitive Forward Surge Current Uni-Directional Only

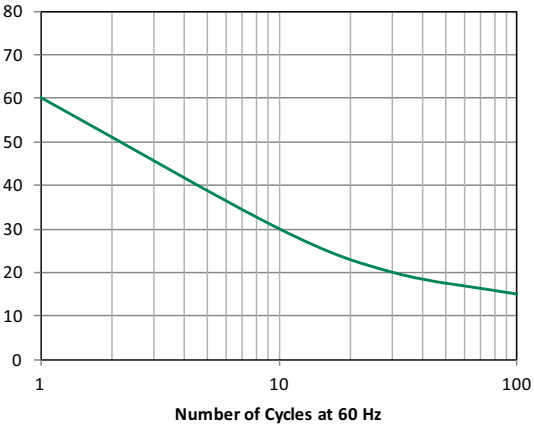
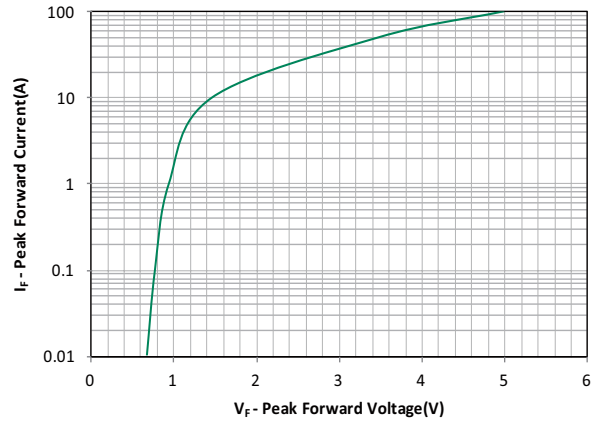
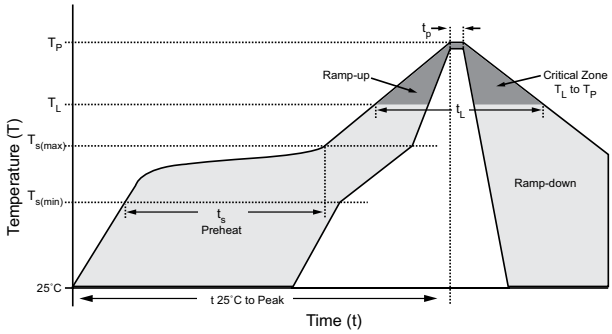


Figure 8 - Peak Forward Voltage Drop vs Peak Forward Current (typical values)



Soldering Parameters

Reflow Condition		Lead–free assembly
Pre Heat	- Temperature Min ($T_{s(min)}$)	150°C
	- Temperature Max ($T_{s(max)}$)	200°C
	- Time (min to max) (t_s)	60 – 180 secs
Average ramp up rate (Liquidus Temp (T_A) to peak		3°C/second max
$T_{S(max)}$ to T_A - Ramp-up Rate		3°C/second max
Reflow	- Temperature (T_A) (Liquidus)	217°C
	- Time (min to max) (t_s)	60 – 150 seconds
Peak Temperature (T_P)		$260^{+0/-5}$ °C
Time within 5°C of actual peak Temperature (t_p)		20 – 40 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature (T_P)		8 minutes Max.
Do not exceed		260°C



Physical Specifications

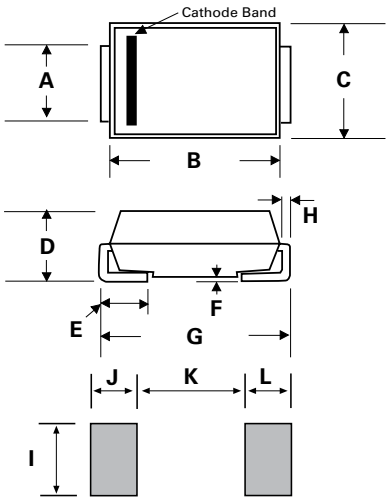
Weight	0.002 ounce, 0.061 gram
Case	JEDEC DO-214AC Molded Plastic over glass passivated junction
Polarity	Color band denotes cathode except Bipolar
Terminal	Matte Tin-plated leads, Solderable per JESD22-B102

Environmental Specifications

High Temp. Storage	JESD22-A103
HTRB	JESD22-A108
Temperature Cycling	JESD22-A104
MSL	JEDEC-J-STD-020, Level 1
H3TRB	JESD22-A101
RSH	JESD22-A111

Dimensions

DO-214AC (SMA)



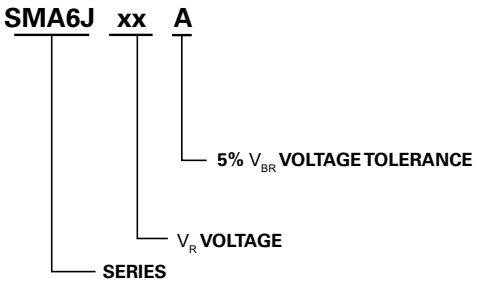
Dimensions	Inches		Millimeters	
	Min	Max	Min	Max
A	0.049	0.065	1.250	1.650
B	0.157	0.181	3.990	4.600
C	0.095	0.110	2.400	2.790
D	0.075	0.090	1.900	2.290
E	0.030	0.060	0.780	1.520
F	-	0.008	-	0.203
G	0.189	0.208	4.800	5.280
H	0.006	0.012	0.152	0.305
I	0.070	-	1.800	-
J	0.082	-	2.100	-
K	-	0.090	-	2.300
L	0.082	-	2.100	-

Revised: 11/20/15

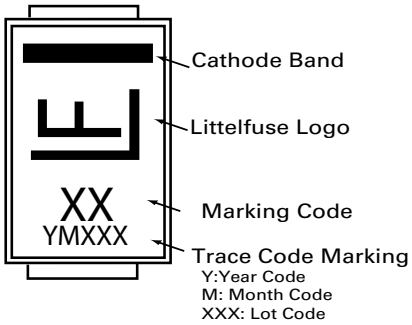
Transient Voltage Suppression Diodes

Surface Mount – 600W > SMA6J series

Part Numbering System



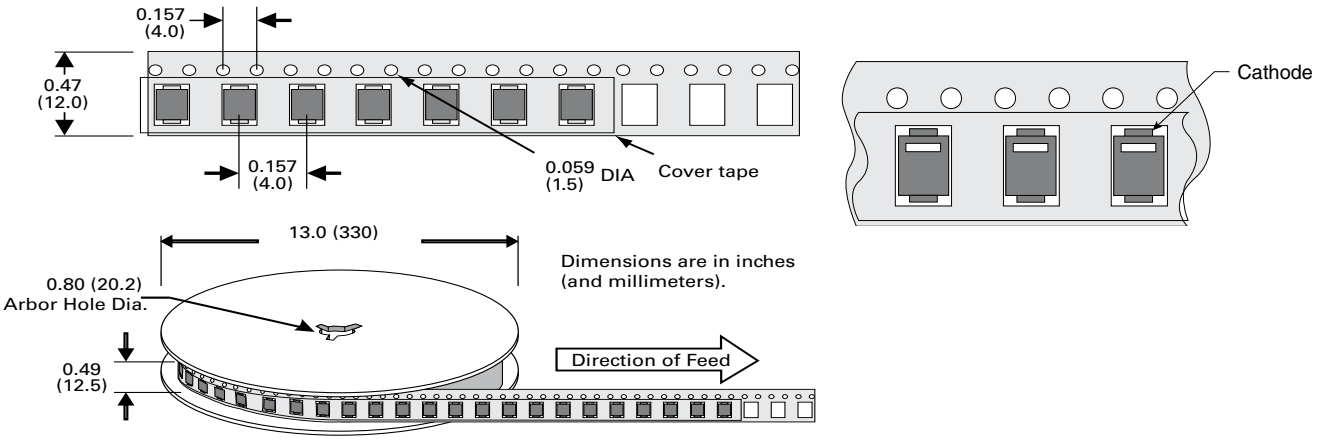
Part Marking System



Packaging

Part number	Component Package	Quantity	Packaging Option	Packaging Specification
SMA6JxxX	DO-214AC	5000	Tape & Reel - 12mm tape/13" reel	EIA RS-481

Tape and Reel Specification



Revised: 11/20/15